Special Issue

Current Techniques in Dental Implants

Message from the Guest Editors

The integration of digital twin technology into dental implantology represents a transformative approach to modern dentistry. By leveraging advanced 3D imaging, artificial intelligence (AI), and simulation techniques, digital twins enable the creation of highly accurate virtual models that mimic the biomechanics of dental implants within a patient's unique anatomical context. These models allow for the prediction of surgical outcomes, personalized treatment planning, and real-time adjustments during procedures, thereby enhancing the precision and success rate of implant placements. This Special Issue will explore the latest developments, applications, and future directions in digital twin technology in dental implantology, aiming to bridge the gap between virtual simulations and clinical reality. Contributions are invited on topics such as AI-driven diagnostics, predictive modeling, and the integration of digital workflows into implant dentistry.

Guest Editors

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Deadline for manuscript submissions

closed (20 April 2025)

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About the Journal

Message from the Editor-in-Chief

As the world of science becomes ever more specialized, researchers may lose themselves in the deep forest of the ever increasing number of subfields being created. This open access journal Applied Sciences has been started to link these subfields, so researchers can cut through the forest and see the surrounding, or quite distant fields and subfields to help develop his/her own research even further with the aid of this multi-dimensional network.

Editor-in-Chief

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